

L Number	Hits	Search Text	DB	Time stamp
101	0	wafer same photoexcitation same galvanic	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 13:39
102	1	wafer same photoexcitation same wavelength	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 13:40
103	84	wafer and photoexcitation and wavelength	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:05
104	121	wafer and electromotive and wavelength	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:04
105	121	wafer and photoexcitation	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 14:13
106	489	substrate and electromotive and wavelength	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:05
107	120	substrate and photoexcitation and wavelength and clean\$4	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:05
108	750	substrate same (laser or irradiated or irradiating) same clean\$4 same (UV or ultraviolet or wavelength)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:11
109	12	substrate same (laser or irradiated or irradiating) same clean\$4 same (UV or ultraviolet or wavelength) same wiring	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:10
110	290	substrate same (laser or irradiated or irradiating) same clean\$4 same wavelength	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:25
111	105	wafer same (laser or irradiated or irradiating) same clean\$4 same wavelength	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:34
112	695	wafer and wiring and (laser or irradiated or irradiating) and clean\$4 and wavelength	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:36
113	184	wafer and wiring and (laser or irradiated or irradiating) and clean\$4 and "500 nm"	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:56
114	1	wafer and wiring and (laser or irradiated or irradiating) and clean\$4 and wavelength	USPAT	2004/08/18 15:39
115	695		USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 15:57
116	40	wafer and wiring and (laser or irradiated or irradiating) and clean\$4 and wavelength and "PN junction"	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 16:05
117	695	wafer and wiring and (laser or irradiated or irradiating) and clean\$4 and wavelength	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 16:06
118	69	wafer and wiring and (laser or irradiated or irradiating) and clean\$4 and wavelength and CMP	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/08/18 16:06
119	1		USPAT	2004/08/18 16:06